

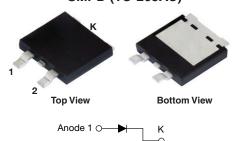
AUTOMOTIVE

ROHS

HALOGEN FREE

# Hyperfast Rectifier, 2 x 10 A FRED Pt®

### eSMP<sup>®</sup> Series SMPD (TO-263AC)



Cathode

#### LIKNKS TO ADDITIONAL RESOURCES

Anode 2 O-



PRIMARY CHARACTERISTICS				
I <sub>F(AV)</sub>	2 x 10 A			
V <sub>R</sub>	200 V			
V <sub>F</sub> at I <sub>F</sub>	0.77 V			
t <sub>rr</sub>	25 ns			
T <sub>J</sub> max.	175 °C			
Package	SMPD (TO-263AC)			
Circuit configuration	Common cathode			

#### **FEATURES**

Hyperfast recovery time, reduced Q<sub>rr</sub>, and soft recovery



- Specified for output and snubber operation
- Low forward voltage drop
- · Low leakage current
- Meets MSL level 1, per J-STD-020, LF maximum peak
- of 260 °C

   AEC-Q101 qualified, meets JESD 201 class 2 whisker test
- Material categorization: for definitions of compliance please see <a href="https://www.vishay.com/doc?99912">www.vishay.com/doc?99912</a>

#### **DESCRIPTION / APPLICATIONS**

State of the art hyperfast recovery rectifiers specifically designed with optimized performance of forward voltage drop and hyperfast recovery time.

The planar structure and the platinum doped life time control guarantee the best overall performance, ruggedness, and reliability characteristics.

These devices are intended for use in the output rectification stage of SMPS, telecom, DC/DC converters as well as freewheeling diode in low voltage inverters and chopper motor drives.

Their extremely optimized stored charge and low recovery current minimize the switching losses and reduce power dissipation in the switching element.

#### **MECHANICAL DATA**

Case: SMPD (TO-263AC)

Molding compound meets UL 94 V-0 flammability rating

Halogen-free, RoHS-compliant

Terminals: matte tin plated leads, solderable per

J-STD-002

ABSOLUTE MAXIMUM RATINGS					
PARAMETER		SYMBOL	TEST CONDITIONS	VALUES	UNITS
Peak repetitive reverse voltage		$V_{RRM}$		200	V
A	per device	I <sub>F(AV)</sub>	T <sub>solder pad</sub> = 152 °C	20	
Average rectified forward current	per diode			10	
Non-vonetitive needs or was a revent	per device	I <sub>FSM</sub>	T <sub>J</sub> = 25 °C, 6 ms square pulse	210	A
Non-repetitive peak surge current	per diode			110	

<b>ELECTRICAL SPECIFICATIONS</b> (T <sub>J</sub> = 25 °C unless otherwise specified)						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Breakdown voltage, blocking voltage	$V_{BR}, V_{R}$	I <sub>R</sub> = 100 μA	200	-	-	
Converd veltage new diede	V <sub>F</sub>	I <sub>F</sub> = 10 A	-	0.94	1.05	V
Forward voltage, per diode		I <sub>F</sub> = 10 A, T <sub>J</sub> = 150 °C	-	0.77	0.87	
Reverse leakage current, per diode I <sub>R</sub>	_	V <sub>R</sub> = V <sub>R</sub> rated	-	-	2	
	ЧR	$T_J = 150 ^{\circ}\text{C},  V_R = V_R  \text{rated}$	-	10	150	μA
Junction capacitance, per diode	C <sub>T</sub>	V <sub>R</sub> = 200 V	-	30	-	pF



<b>DYNAMIC RECOVERY CHARACTERISTICS</b> (T <sub>J</sub> = 25 °C unless otherwise specified)							
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNITS
		$I_F = 1 A, dI_F/dt = 50 A$	/μs, V <sub>R</sub> = 30 V	-	25	-	
Reverse recovery time t <sub>rr</sub>	t <sub>rr</sub>	$I_F = 0.5 \text{ A}, I_R = 1 \text{ A}, I_{rr} = 0.25 \text{ A}$		-	-	25	
		T <sub>J</sub> = 25 °C	I <sub>F</sub> = 10 A, dI <sub>F</sub> /dt = 200 A/μs, V <sub>R</sub> = 160 V	-	22	-	ns
		T <sub>J</sub> = 125 °C		-	35	-	
Peak recovery current	I <sub>RRM</sub>	T <sub>J</sub> = 25 °C		=.	2.5	-	Α
		T <sub>J</sub> = 125 °C		-	5	-	
Daylarda waaayami aharaa	Q <sub>rr</sub>	T <sub>J</sub> = 25 °C		-	25	-	nC
Reverse recovery charge		T <sub>J</sub> = 125 °C		-	85	-	110

THERMAL - MECHANICAL SPECIFICATIONS						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Maximum junction and storage temperature range	T <sub>J</sub> , T <sub>Stg</sub>		-55	-	+175	°C
Thermal resistance, per diode junction to mount	$R_{thJM}$		-	1.8	2.4	°C/W
Approximate weight				0.55		g
Approximate weight				0.02		oz.
Marking device		Case style SMPD (TO-263AC)	20CDH02			

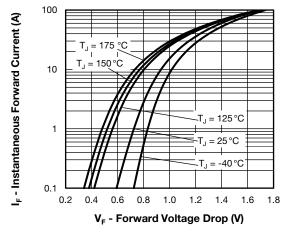


Fig. 1 - Typical Forward Voltage Drop Characteristics

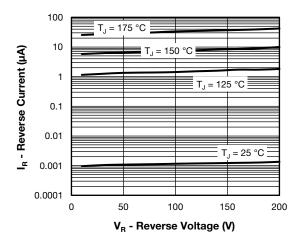


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

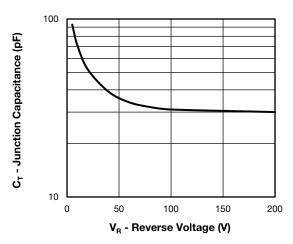


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

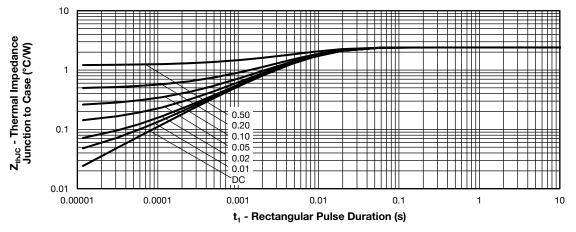


Fig. 4 - Maximum Thermal Impedance Z<sub>thJC</sub> Characteristics

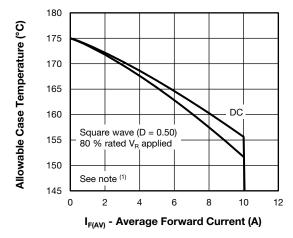


Fig. 5 - Maximum Allowable Case Temperature vs.
Average Forward Current

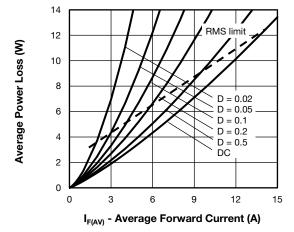


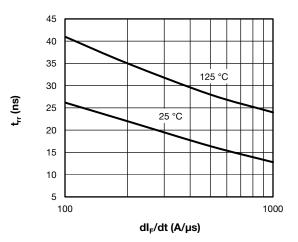
Fig. 6 - Forward Power Loss Characteristics

#### Note

 $<sup>\</sup>begin{array}{ll} \text{(1)} & \text{Formula used: } T_C = T_J - (Pd + Pd_{REV}) \times R_{thJC}; \\ Pd = \text{forward power loss} = I_{F(AV)} \times V_{FM} \text{ at } (I_{F(AV)}/D) \text{ (see fig. 5)}; \\ Pd_{REV} = \text{inverse power loss} = V_{R1} \times I_R \text{ (1 - D); } I_R \text{ at } V_{R1} = \text{rated } V_R \\ \end{array}$ 

#### www.vishay.com

# Vishay Semiconductors





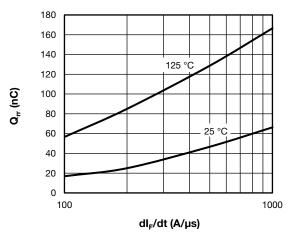
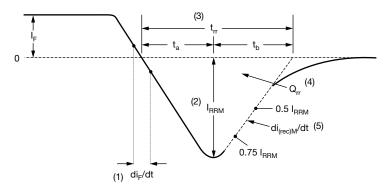


Fig. 8 - Typical Stored Charge vs. dl<sub>E</sub>/dt



- (1) di<sub>F</sub>/dt rate of change of current through zero crossing
- (2) I<sub>RRM</sub> peak reverse recovery current
- (3)  $\rm t_{rr}$  reverse recovery time measured from zero crossing point of negative going  $\rm I_{r}$  to point where a line passing through 0.75  $\rm I_{RRM}$  and 0.50  $\rm I_{RRM}$  extrapolated to zero current.
- (4)  $\mathbf{Q}_{rr}$  area under curve defined by  $\mathbf{t}_{rr}$  and  $\mathbf{I}_{RRM}$

$$Q_{rr} = \frac{t_{rr} \times I_{RRM}}{2}$$

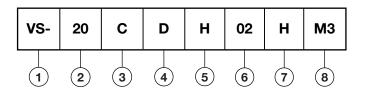
(5)  $di_{(rec)M}/dt$  - peak rate of change of current during  $t_b$  portion of  $t_{rr}$ 

Fig. 9 - Reverse Recovery Waveform and Definitions



### **ORDERING INFORMATION TABLE**

Device code



1 - Vishay Semiconductors product

2 - Current rating (20 A)

Circuit configuration:

C = common cathode

- D = SMPD package

**5** - Process type,

H = hyperfast recovery

6 - Voltage code (02 = 200 V)

7 - H = AEC-Q101 qualified

8 - M3 = halogen-free, RoHS-compliant, and terminations lead (Pb)-free

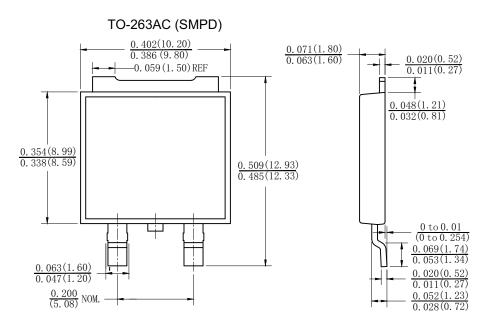
ORDERING INFORMATION (Example)					
PREFERRED P/N	QUANTITY PER REEL	MINIMUM ORDER QUANTITY	PACKAGING DESCRIPTION		
VS-20CDH02HM3/I	2000	2000	13" diameter plastic tape and reel		

LINKS TO RELATED DOCUMENTS				
Dimensions	www.vishay.com/doc?95604			
Part marking information	www.vishay.com/doc?95566			
Packaging information	www.vishay.com/doc?88869			
SPICE model	www.vishay.com/doc?96572			

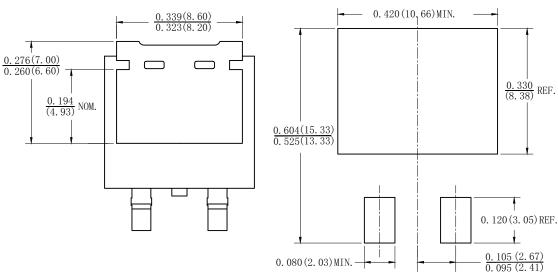


# TO-263AC (SMPD)

### **DIMENSIONS** in inches (millimeters)



### Mounting Pad Layout





## **Legal Disclaimer Notice**

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